



Material Content Data Sheet



Sales Product Name		BSO203P H		Issued		27. September 2017		
MA#		MA000719934						
Package		PG-DSO-8-40		Weight*		83.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.327	4.01	4.01	40072	40072
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		118	
	non noble metal	zinc	7440-66-6	0.039	0.05		473	
	non noble metal	iron	7439-89-6	0.785	0.95		9456	
wire	non noble metal	copper	7440-50-8	31.880	38.40	39.41	383951	393998
	non noble metal	copper	7440-50-8	0.205	0.25	0.25	2473	2473
	encapsulation	organic material	carbon black	1333-86-4	0.224	0.27		2698
plastics	plastics	epoxy resin	-	6.945	8.36		83643	
	inorganic material	silicondioxide	60676-86-0	37.638	45.31	53.94	453290	539631
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9801	9801
plating	noble metal	silver	7440-22-4	0.063	0.08	0.08	757	757
glue	plastics	epoxy resin	-	0.165	0.20		1990	
	noble metal	silver	7440-22-4	0.936	1.13	1.33	11278	13268
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com